

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



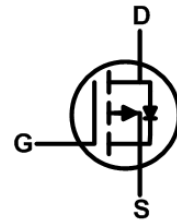
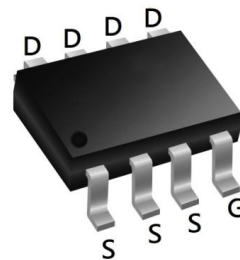
| BVDSS | RDSON | ID |
|-------|--------|-------|
| -30V | 9.5 mΩ | -12 A |

General Description

The SL12P03S is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The SL12P03S meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------|---|------------|------------|
| V_{DS} | Drain-Source Voltage | -30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -12 | A |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -9 | A |
| I_{DM} | Pulsed Drain Current ² | -46 | A |
| EAS | Single Pulse Avalanche Energy ³ | 55 | mJ |
| I_{AS} | Avalanche Current | -50 | A |
| $P_D @ T_A = 25^\circ C$ | Total Power Dissipation ⁴ | 4.5 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|---|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 75 | $^\circ C/W$ |
| | Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$) | --- | 40 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 24 | $^\circ C/W$ |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|--|--|------|------|-----------|------------|
| Off Characteristic | | | | | | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -30 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-30V, V_{GS}=0V,$ | - | - | -1 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS}=0V, V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.0 | -1.6 | -2.5 | V |
| $R_{DS(on)}$ | Static Drain-Source on-Resistance Note3 | $V_{GS}=-10V, I_D=-10A$ | - | 9.5 | 14 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-5A$ | - | 17 | 24 | |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=-15V, V_{GS}=0V,$ $f=1.0MHz$ | - | 1770 | - | pF |
| C_{oss} | Output Capacitance | | - | 233 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 206 | - | pF |
| Q_g | Total Gate Charge | $V_{DS}=-15V, I_D=-5A,$ $V_{GS}=-10V$ | - | 22 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 1.0 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 1.8 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD}=-15V, I_D=-10A,$ $V_{GS}=-10V, R_{GEN}=2.5\Omega$ | - | 9 | - | ns |
| t_r | Turn-on Rise Time | | - | 13 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 48 | - | ns |
| t_f | Turn-off Fall Time | | - | 20 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -15 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -60 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS}=0V, I_S=-15A$ | - | -0.8 | -1.2 | V |
| t_{rr} | Reverse Recovery Time | $T_J=25^\circ\text{C},$ | - | 64 | - | ns |
| Q_{rr} | Reverse Recovery Charge | $V_{DD}=-24V, I_F=-2.8A,$ $di/dt=-100A/\mu s$ | - | 25 | - | nC |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}, V_{GS}=10V, R_G=25\Omega, L=0.5mH, I_{AS}=-12.7A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

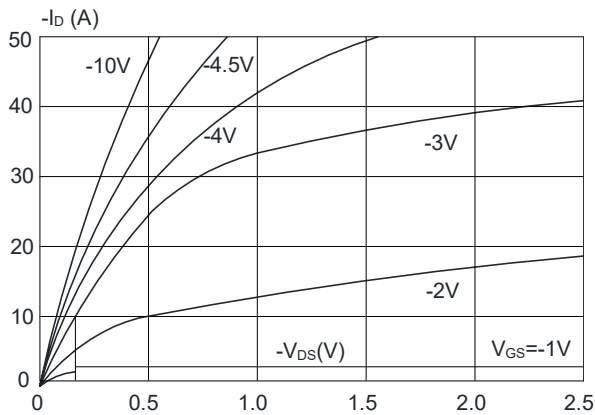


Figure 2: Typical Transfer Characteristics

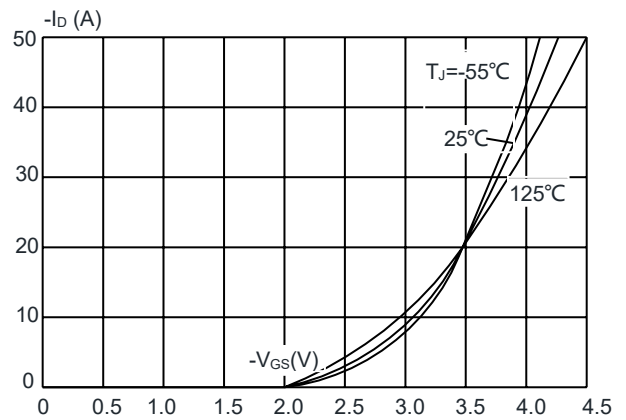


Figure 3: On-resistance vs. Drain Current

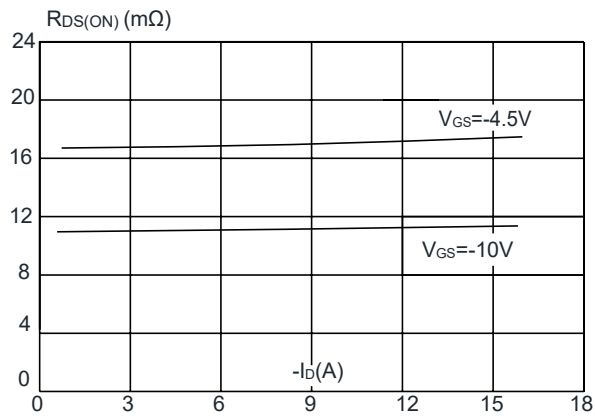


Figure 4: Body Diode Characteristics

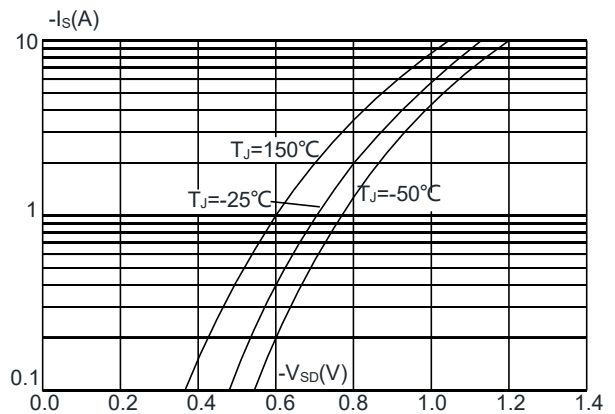


Figure 5: Gate Charge Characteristics

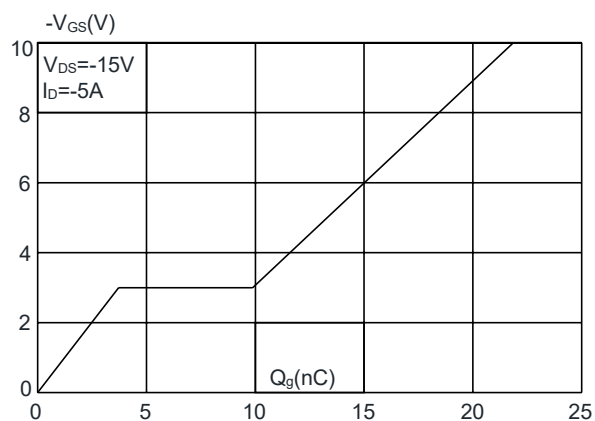
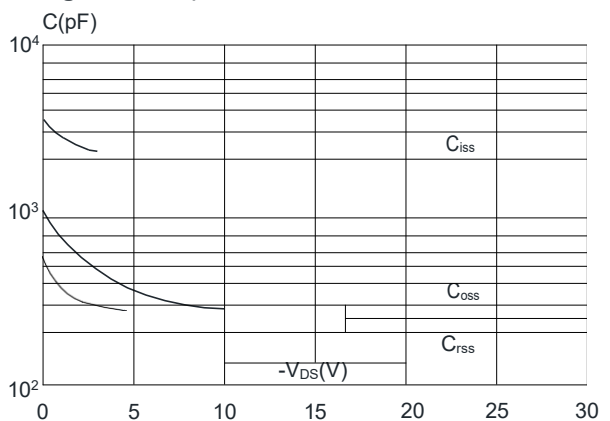
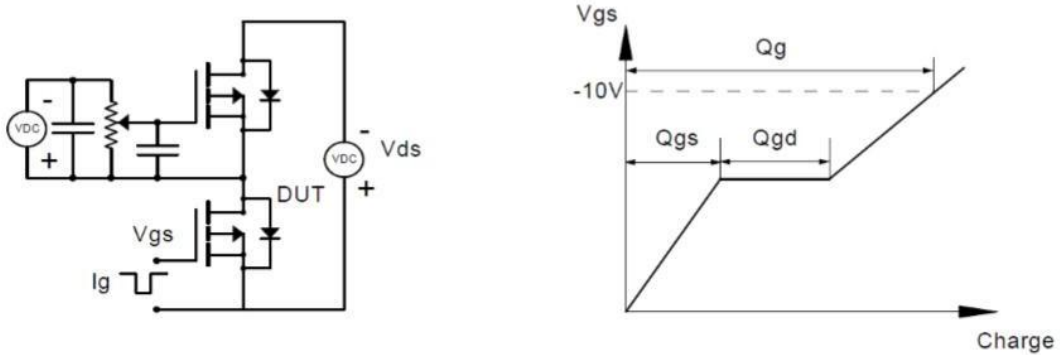


Figure 6: Capacitance Characteristics

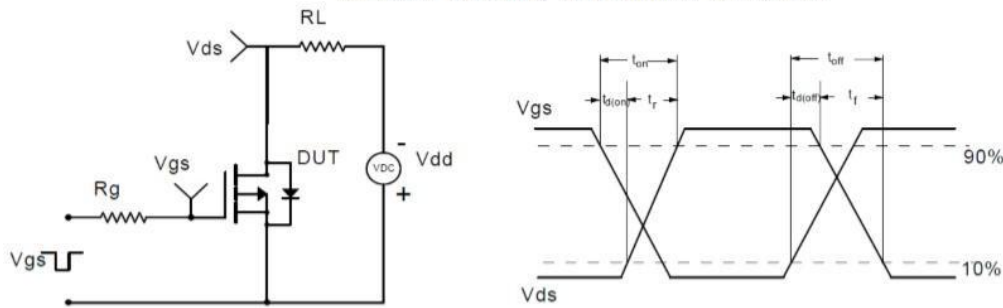


Test Circuit

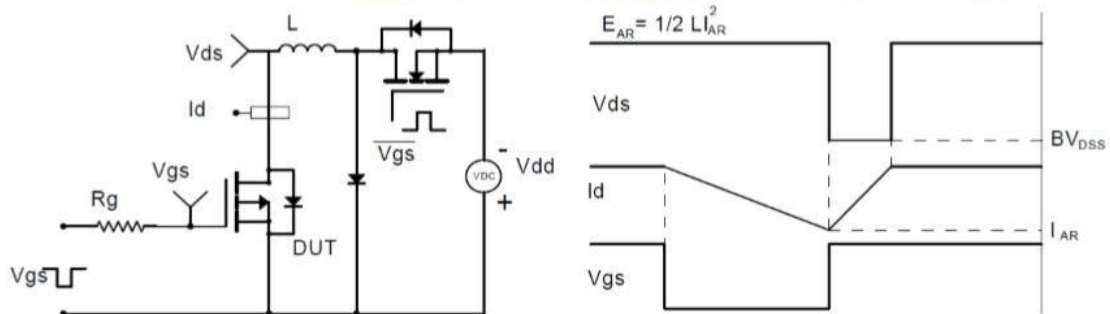
Gate Charge Test Circuit & Waveform



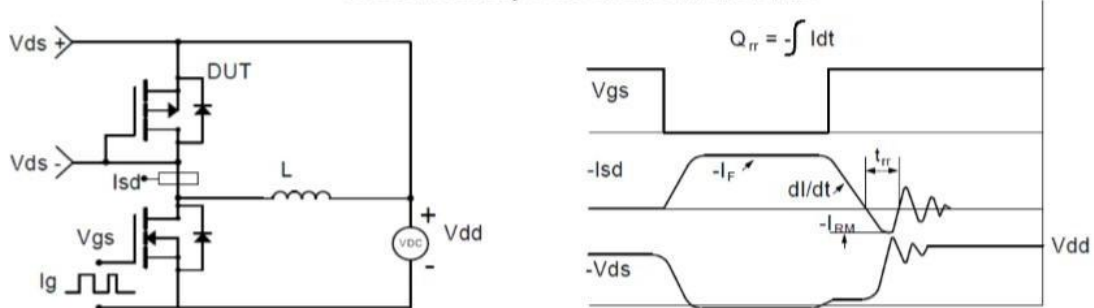
Resistive Switching Test Circuit & Waveforms



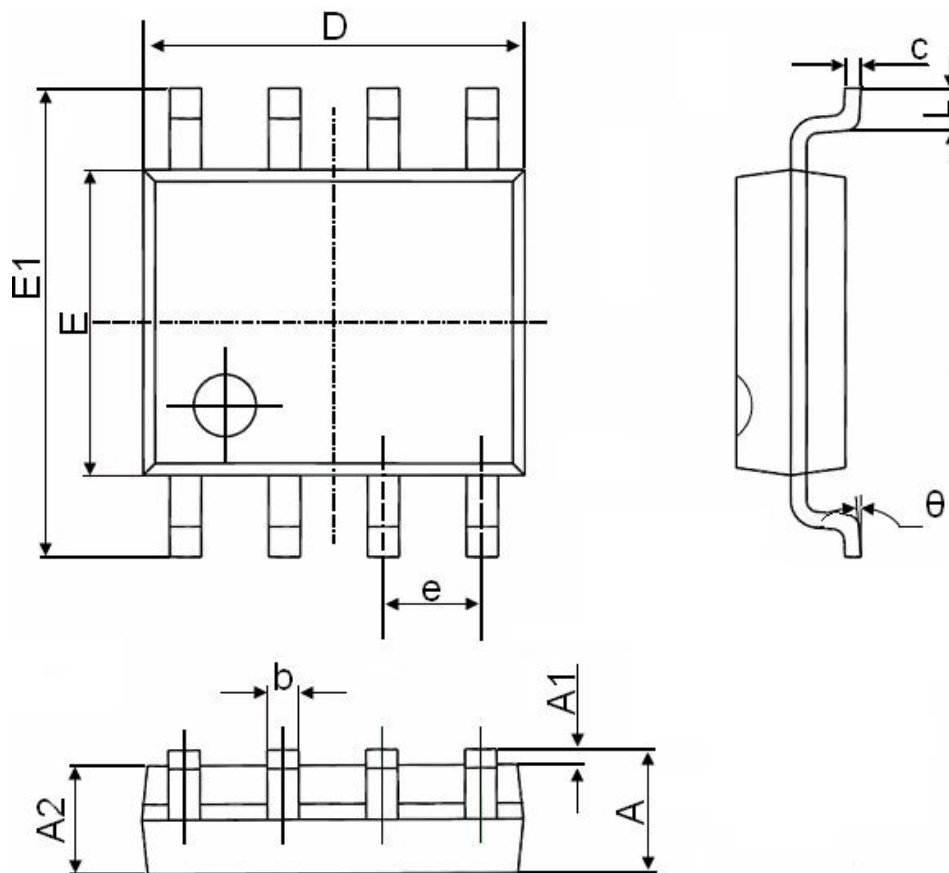
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOP-8 Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.200 |
| E | 3.800 | 4.000 | 0.150 | 0.157 |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |